TOP VIEW

33 | B | C | 33 | A1 CORNER | 29.6±0.1 | 29.6±0.1 | 4X ⌓ 0.2

BOTTOM VIEW

31X 1 | 0.5 | 0.5 | 31X 1 | A1 CORNER | 1023X ø0.7 / ø0.4 (4) | ⌖ ø0.3 Ⓜ A B C | ø0.15 Ⓜ A

SIDE VIEW

1023X ⌓ 0.2 A | // 0.25 A | // 0.35 A (6) | A SEATING PLANE (5) | 0.60 / 0.35 | 3.38 MAX

© NXP SEMICONDUCTORS N.V.
ALL RIGHTS RESERVED

MECHANICAL OUTLINE

PRINT VERSION NOT TO SCALE

TITLE: 1023 I/O, FC BGA,
33 X 33 PKG, WITH FOOTED LID
1 MM PITCH, WITH CAP ZONES

DOCUMENT NO: 98ARE10679D REV: E

STANDARD: NON-JEDEC

SOT1619-1 05 JAN 2016

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.

2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M–1994.

3. ALL DIMENSIONS ARE SYMMETRIC ACROSS THE PACKAGE CENTER LINES, UNLESS DIMENSIONED OTHERWISE.

4. MAXIMUM SOLDER BALL DIAMETER MEASURED PARELLEL TO DATUM A.

5. DATUM A, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

6. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

© NXP SEMICONDUCTORS N.V. ALL RIGHTS RESERVED	MECHANICAL OUTLINE	PRINT VERSION NOT TO SCALE
TITLE: 1023 I/O, FC BGA, 33 X 33 PKG, WITH FOOTED LID 1 MM PITCH, WITH CAP ZONES	DOCUMENT NO: 98ARE10679D	REV: E
	STANDARD: NON–JEDEC	
	SOT1619–1	05 JAN 2016